# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE: **NEW ASSIGNMENT** 

NATURE OF CONVEYANCE: SECURITY AGREEMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Endicott Interconnect Technologies, Inc.	09/30/2008

#### RECEIVING PARTY DATA

Name:	JPMorgan Chase Bank, N.A., as Administrative Agent		
Street Address:	10 South Dearborn Street		
City:	Chicago		
State/Country:	ILLINOIS		
Postal Code:	60603		

#### PROPERTY NUMBERS Total: 128

Property Type	Number
Application Number:	12081051
Application Number:	12081042
Application Number:	11882473
Application Number:	11652633
Application Number:	11797236
Application Number:	11650520
Application Number:	12010335
Application Number:	12010469
Application Number:	12010004
Application Number:	11598647
Application Number:	12007178
Application Number:	12003299
Application Number:	11590888
Application Number:	11806685
Application Number:	11541776
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Application Number:	11976629
Application Number:	11500328
Application Number:	11492029
Application Number:	11905188
Application Number:	11902976
Application Number:	11896786
Application Number:	11454896
Application Number:	11889668
Application Number:	11438424
Application Number:	11822573
Application Number:	11396711
Application Number:	11802434
Application Number:	11797232
Application Number:	11730761
Application Number:	11305073
Application Number:	11253659
Application Number:	11634287
Application Number:	11607973
Application Number:	11352279
Application Number:	11352276
Application Number:	11244180
Application Number:	11482945
Application Number:	11455183
Application Number:	11110920
Application Number:	11401401
Application Number:	11086324
Application Number:	11429990
Application Number:	11390386
Application Number:	11215206
Application Number:	11324273
Application Number:	11031085
Application Number:	11350777
Application Number:	11334445
Application Number:	11265287
Application Number:	10860067
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Application Number:  Application Number:  Patent Number:  Patent Number:  Patent Number:  Patent Number:  Patent Number:  Patent Number:	10740500       10449019       10868066       7416996       7416972       7384856       7383629       7381587
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Patent Number:	7377033
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Patent Number:	7343674
Patent Number:	7342183
Patent Number:	7334323
Patent Number:	7332818
Patent Number:	7332212
Patent Number:	7328502
Patent Number:	7326643
Patent Number:	7307022
Patent Number:	7294791
Patent Number:	7293355
Patent Number:	7292055
Patent Number:	7270845
Patent Number:	7253518
Patent Number:	7253502
Patent Number:	7235745
Patent Number:	7211470
Patent Number:	7211289
Patent Number:	7209368
Patent Number:	7176383
Patent Number:	7169313
Patent Number:	7163847
Patent Number:	7161810
Patent Number:	7157647
Patent Number:	7157646 <b>PATENT</b>

Patent Number:	7152319
Patent Number:	7145221
Patent Number:	7142121
Patent Number:	7129732
Patent Number:	7109732
Patent Number:	7091066
Patent Number:	7087846
Patent Number:	7087441
Patent Number:	7084014
Patent Number:	7078816
Patent Number:	7071423
Patent Number:	7063762
Patent Number:	7047630
Patent Number:	7045897
Patent Number:	7035113
Patent Number:	7025607
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Patent Number:	6995322
Patent Number:	6992896
Patent Number:	6964884
Patent Number:	6958106
Patent Number:	6905589
Patent Number:	6900392
Patent Number:	6872894
Patent Number:	6828514
Patent Number:	6815837
Patent Number:	6809269
Application Number:	11907006
Application Number:	11907004
Application Number:	11976468
Application Number:	12007820
Application Number:	12148271
Application Number:	11730212
Application Number:	11727314

Application Number:	11882149
Application Number:	11783306
Application Number:	11808140
Application Number:	11730404
Application Number:	11878673
Application Number:	12007704
Application Number:	12078206
Application Number:	12215079

#### **CORRESPONDENCE DATA**

Fax Number: (214)981-3400

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

214-981-3483 Phone: Email: dclark@sidley.com Correspondent Name: Dusan Clark, Esq. Address Line 1: Sidley Austin LLP

Address Line 2: 717 N. Harwood St., Suite 3400

Dallas, TEXAS 75201 Address Line 4:

ATTORNEY DOCKET NUMBER:	36084-36710
NAME OF SUBMITTER:	Dusan Clark

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#### CONFIRMATORY GRANT OF SECURITY INTEREST IN UNITED STATES PATENTS

THIS CONFIRMATORY GRANT OF SECURITY INTEREST IN UNITED STATES PATENTS (as the same may be amended, restated, supplemented or otherwise modified from time to time, the "<u>Confirmatory Grant</u>") is made effective as of September 30, 2008 by and from ENDICOTT INTERCONNECT TECHNOLOGIES, INC., a New York corporation (the "<u>Grantor</u>"), to and in favor of JPMORGAN CHASE BANK, N.A., for itself and as Administrative Agent for the Lenders (as defined in the Credit Agreement referenced below) (in such capacities, the "<u>Grantee</u>").

WHEREAS, Grantor, the Lenders and Grantee have entered into a Credit Agreement dated as of September 30, 2008 (as may be amended, restated, supplemented or otherwise modified from time to time, the "Credit Agreement").

WHEREAS, the Grantor has entered into a Pledge and Security Agreement dated as of September 30, 2008 (as may be amended, restated, supplemented or otherwise modified from time to time, the "Security Agreement").

WHEREAS, the Grantor owns the patents listed on Exhibit A attached hereto (the "Patents"), which Patents are registered or pending with the United States Patent and Trademark Office.

WHEREAS, this Confirmatory Grant has been granted in conjunction with the security interest granted under the Security Agreement to Grantee for the benefit of the Holders of Secured Obligations. The rights and remedies of Grantee with respect to the security interest granted herein are without prejudice to and are in addition to those set forth in the Security Agreement and the other Loan Documents, all terms and provisions of which are incorporated herein by reference. In the event that any provisions of this Confirmatory Grant are deemed to conflict with the Security Agreement, the provisions of the Security Agreement shall govern.

NOW, THEREFORE, in consideration of the mutual covenants and agreements set forth herein and for other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, it is hereby agreed that:

1) <u>Definitions</u>. All capitalized terms not defined herein shall have the respective meaning given to them in the Credit Agreement.

#### 2) The Security Interest.

- (a) This Confirmatory Grant is made to secure the satisfactory performance and payment of (i) all the Secured Obligations and (ii) all of the obligations and liabilities of the Subsidiary Guarantors under the Guaranty. Upon the payment in full of all Secured Obligations (other than Unliquidated Obligations), Grantee shall promptly, upon such satisfaction, execute, acknowledge, and deliver to Grantor all reasonably requested instruments in writing releasing the security interest in the Patents acquired under the Security Agreement and this Confirmatory Grant.
- (b) The Grantor hereby grants to Grantee a security interest in (1) all of Grantor's right, title and interest in and to the Patents now owned or from time to time after the date hereof owned or acquired by the Grantor, together with (2) all proceeds of the Patents, and (3) all causes of action arising prior to or after the date hereof for infringement of the Patents or unfair competition regarding the same.

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- 3) Counterparts. This Confirmatory Grant may be executed in any number of counterparts and by different parties in separate counterparts, each of which when so executed shall be deemed to be an original and all of which taken together shall constitute one and the same agreement. Signature pages may be detached from multiple separate counterparts and attached to a single counterpart.
- 4) Governing Law. This Confirmatory Grant and the rights and obligations of the parties hereto shall be governed by, and construed and interpreted in accordance with, the law of the State of New York.

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IN WITNESS WHEREOF, the Grantor has executed this Confirmatory Grant effective as of the date first written above.

ENDICOTT INTERCONNECT TECHNOLOGIES, INC., as Grantor

Name: STEVEN P. BURKE

Title: CF6

STATE OF NEW YORK )
Westcheser County )

On September 29, 2008, before me, Jacqueline Tulin Notary Public, personally appeared Steven . But the personally known to me to be the person whose name is subscribed to the within instrument and acknowledged to me that he executed the same in his authorized capacity, and that by his signature on the instrument, the person, or the entity upon behalf of which the person acted, executed the instrument.

(SEAL)

Motary Public, State of New You

My Commission Expires:

JACQUELINE J. WARNER
Notary Public, State of New York
No. 02WA6055940
Residing in Westchester County
My Commission Expires 3/12/20\_//

Signature Page for Grant of Security Interest in United States Patents

NO.   PUBLICATION NO/   SERIAL NO.   SERIA	ECONOMIC CONTROL		it A-Schedule of	
SERIAL NO		PATENT NO.	DATE	
1.   20080191354   12081051   8/14/2008   WITH P-ARAMID   DIELECTRIC LAYERS AND   METHOD OF MAKING   SAME   WITH P-ARAMID   DIELECTRIC LAYERS AND   METHOD OF MAKING   SAME   WITH P-ARAMID   DIELECTRIC LAYERS AND   METHOD OF MAKING   SAME   WITH P-ARAMID   DIELECTRIC LAYERS AND   METHOD OF MAKING   SAME   WITH P-ARAMID   DIELECTRIC LAYERS AND   METHOD OF MAKING   SAME   SAME   WITH DIRECTIONAL   COOLING   METHOD OF INSPECTING   ARTICLES USING IMAGING   INSPECTION APPARATUS   WITH DIRECTIONAL   COOLING   METHOD OF PROVIDING A   PRINTED CIRCUIT BOARD   WITH AN EDGE   CONNECTION PORTION   AND/OR A PLURALITY OF   CAVITIES THEREIN   WITH METAL COMPONENT   AND ELECTRICAL   ASSEMBLY AND   INFORMATION HANDLING   SYSTEM UTILIZING SAID   CIRCUITIZED SUBSTRATE   WITH METAL COMPONENT   AND ELECTRICAL   ASSEMBLY AND   INFORMATION HANDLING   SYSTEM UTILIZING SAID   CIRCUITIZED SUBSTRATE   WITH SOLDER BALLS   HAVING ROUGHENED   SUBSTRATE   WITH SOLDER BALLS   HAVING ROUGHENED   SUFFACES, METHOD OF MAKING   CIRCUITIZED SUBSTRATE   WITH SOLDER BALLS   HAVING ROUGHENED   SUBSTRATE, AND   METHOD OF MAKING   CIRCUITIZED SUBSTRATE   WITH SOLDER BALLS   HAVING ROUGHENED   SUBSTRATE, AND   METHOD OF MAKING   MULTIPLE CIRCUITIZED   SUBSTRATE, AND   METHOD OF MAKING   MULTIPLE CIRCUITIZED   SUBSTRATE   ASSEMBLY INCLUDING   SAID CIRCUITIZED   SUBSTRATE   ASSEMBLY   METHOD OF MAKING   MULTIPLE CIRCUITIZED   SUBSTRATE   ASSEMBLY   METHOD OF MAKING   MULTIPLE CIRCUITIZED   SUBSTRATE   ASSEMBLY   METHOD OF MAKING   METHOD OF MAKING   MULTIPLE CIRCUITIZED   SUBSTRATE   ASSEMBLY   METHOD OF MAKING   METHOD OF	NO.	<b>化排列的表示</b> 主册 (1)		I I I I I I I
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METHOD OF MAKING   SAME		12081051	4/10/2008	WITH P-ARAMID
2.   20080191353   8/14/2008   MULTILAYERED   CIRCUITIZED SUBSTRATE   WITH P-ARAMID   DIELECTRIC LAYERS AND   METHOD OF MAKING   SAME     3.   20080170670   7/17/2008   METHOD OF INSPECTING   ARTICLES USING IMAGING   INSPECTION APPARATUS   WITH DIRECTIONAL   COOLING     4.   20080168651   7/17/2008   METHOD OF PROVIDING A   PRINTED CIRCUIT BOARD   WITH AN EDGE   CONNECTION PORTION   AND/OR A PLURALITY OF   CAVITIES THEREIN     5.   20080151515   6/26/2008   METHOD OF MAKING   CIRCUITIZED SUBSTRATE   WITH RESISTOR   INCLUDING MATERIAL   WITH METAL COMPONENT   AND ELECTRICAL   ASSEMBLY AND   INFORMATION HANDLING   SYSTEM UTILIZING SAID   CIRCUITIZED SUBSTRATE   WITH SOLDER BALLS   HAVING ROUGHENED   SURFACES, METHOD OF MAKING   CIRCUITIZED SUBSTRATE   WITH SOLDER BALLS   HAVING ROUGHENED   SURFACES, METHOD OF MAKING   CIRCUITIZED SUBSTRATE   SUBSTRATE, AND   METHOD OF MAKING   CIRCUITIZED   SUBSTRATE, AND   METHOD OF MAKING   SAID CIRCUITIZED   SUBSTRATE, AND   METHOD OF MAKING   MULTIPLE CIRCUITIZED   SUBSTRATE   ASSEMBLY   TO MAKING   MULTIPLE CIRCUITIZED   SUBSTRATE   SUBSTRATE   SUBSTRATE   ASSEMBLY   TO MAKING   MULTIPLE CIRCUITIZED   SUBSTRATE   ASSEMBLY   HIGH SPEED INTERPOSER				DIELECTRIC LAYERS AND
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information handling system utilizing said circuitized substrate  6. 20080164300 7/10/2008 METHOD OF MAKING 11650520 1/8/2007 CIRCUITIZED SUBSTRATE WITH SOLDER BALLS HAVING ROUGHENED SURFACES, METHOD OF MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY  7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				
SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATE  6. 20080164300 7/10/2008 METHOD OF MAKING 11650520 1/8/2007 CIRCUITIZED SUBSTRATE WITH SOLDER BALLS HAVING ROUGHENED SURFACES, METHOD OF MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY  7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				
6. 20080164300 7/10/2008 METHOD OF MAKING 11650520 1/8/2007 CIRCUITIZED SUBSTRATE WITH SOLDER BALLS HAVING ROUGHENED SURFACES, METHOD OF MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY 7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				1
6. 20080164300 7/10/2008 METHOD OF MAKING 11650520 1/8/2007 CIRCUITIZED SUBSTRATE WITH SOLDER BALLS HAVING ROUGHENED SURFACES, METHOD OF MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY 7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				
1/8/2007 CIRCUITIZED SUBSTRATE WITH SOLDER BALLS HAVING ROUGHENED SURFACES, METHOD OF MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY 7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				CIRCUITIZED SUBSTRATE
1/8/2007 CIRCUITIZED SUBSTRATE WITH SOLDER BALLS HAVING ROUGHENED SURFACES, METHOD OF MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY 7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				
WITH SOLDER BALLS HAVING ROUGHENED SURFACES, METHOD OF MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY 7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER	6.	20080164300	7/10/2008	METHOD OF MAKING
HAVING ROUGHENED SURFACES, METHOD OF MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY 7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER		11650520	1/8/2007	CIRCUITIZED SUBSTRATE
SURFACES, METHOD OF MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY  7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				WITH SOLDER BALLS
SURFACES, METHOD OF MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY  7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				HAVING ROUGHENED
MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY 7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				
ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY 7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				, ,
SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY  7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				
SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY  7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER	<u> </u>			
METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY  7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				
MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY  7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				•
7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				
7. 20080142258 6/19/2008 HIGH SPEED INTERPOSER				
	<del>  </del>	20080142258	6/10/2009	
12010333 1/24/2008	/ -			HIGH SPEED INTERPOSER
0 20000120025				METHOD OF MAKING
8. 20080120835 5/29/2008 METHOD OF MAKING	8.		- '	
12010469   1/25/2008   HIGH SPEED INTERPOSER		12010469	1/25/2008	HIGH SPEED INTERPOSER
			# ID D / F C C C	D. TOO D. C. A. T. C.
9.   20080117583   5/22/2008   INFORMATION HANDLING	9.			
12010004   1/18/2008   SYSTEM UTILIZING		12010004	1/18/2008	SYSTEM UTILIZING

NO.	PATENT NO./ PUBLICATION NO./ SERIAL NO.	DATE ISSUED/ DATE FILED	TITLE:
7.4	DERIAL NO.	U-112/14302	CIRCUITIZED SUBSTRATE
			WITH SPLIT CONDUCTIVE
			LAYER
10.	20080110016	5/15/2008	METHOD OF MAKING
'''	11598647	11/14/2006	CIRCUITIZED SUBSTRATE
	110,000		WITH SOLDER PASTE
			CONNECTIONS
11.	20080105457	5/8/2008	CIRCUITIZED SUBSTRATE
	12007178	1/8/2008	WITH SINTERED PASTE
			CONNECTIONS AND
			MULTILAYERED
			SUBSTRATE ASSEMBLY
			HAVING SAID SUBSTRATE
			AS PART THEREOF
12.	20080102562	5/1/2008	METHOD OF MAKING
	12003299	12/21/2007	MULTI-CHIP ELECTRONIC
			PACKAGE WITH REDUCED
			LINE SKEW
13.	20080098595	5/1/2008	METHOD OF MAKING A
	11590888	11/1/2006	CIRCUITIZED SUBSTRATE
			WITH ENHANCED
			CIRCUITRY AND
			ELECTRICAL ASSEMBLY
			UTILIZING SAID
			SUBSTRATE
14.	20080087459	4/17/2008	CIRCUITIZED SUBSTRATE
	11/806,685	6/4/2007	WITH INTERNAL RESISTOR, METHOD OF
			MAKING SAID
		<u> </u>	CIRCUITIZED SUBSTRATE,
	-	1	AND ELECTRICAL
			ASSEMBLY UTILIZING
		ļ	SAID CIRCUITIZED
			SUBSTRATE
15.	20080078570	4/3/2008	HALOGEN-FREE
13.	11541776	10/3/2006	CIRCUITIZED SUBSTRATE
	11341770	10/5/2000	WITH REDUCED THERMAL
			EXPANSION, METHOD OF
			MAKING SAME,
			MULTILAYERED
			SUBSTRATE STRUCTURE
			UTILIZING SAME, AND
			INFORMATION HANDLING
			SYSTEM UTILIZING
16.	20080054476	3/6/2008	CIRCUITIZED SUBSTRATE
	11976629	10/26/2007	WITH INCREASED
			ROUGHNESS CONDUCTIVE
			LAYER AS PART THEREOF
17.	20080038670	2/14/2008	SOLDER MASK
	11500328	8/8/2006	APPLICATION PROCESS
18.	20080026316	1/31/2008	PHOTORESIST

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	PATENT NO./ PUBLICATION NO./	DATE	TIPLE:
NO.	SERIAL NO.	DATE FILED	
	11492029	7/25/2006	COMPOSITION WITH
	11492029	772572000	ANTIBACTERIAL AGENT
19.	20080022520	1/31/2008	METHOD OF MAKING
17.	11905188	9/28/2007	MULTI-LAYERED
	11703100	7,20,200,	CIRCUITIZED SUBSTRATE
			ASSEMBLY
20.	20080020566	1/24/2008	METHOD OF MAKING AN
-0.	11902976	9/27/2007	INTERPOSER
21,	20080003407	1/3/2008	CIRCUITIZED SUBSTRATE
	11896786	9/6/2007	WITH DIELECTRIC LAYER
	110,0100		HAVING DIELECTRIC
			COMPOSITION NOT
			INCLUDING CONTINUOUS
			OR SEMICONTINUOUS
1			FIBERS
22.	20070289773	12/20/2007	HIGH SPEED INTERPOSER
	11454896	6/19/2006	
23.	20070284140	12/13/2007	METHOD OF MAKING
	11889668	8/15/2007	CIRCUITIZED SUBSTRATE
1			WITH IMPROVED
			IMPEDANCE CONTROL
			CIRCUITRY, ELECTRICAL
			ASSEMBLY AND
			INFORMATION HANDLING
			SYSTEM
24.	20070275525	11/29/2007	CAPACITIVE SUBSTRATE
	11438424	5/23/2006	AND METHOD OF MAKING
L			SAME
25.	20070254408	11/1/2007	METHOD OF MAKING
	11822573	7/9/2007	WIREBOND ELECTRONIC
			PACKAGE WITH
			ENHANCED CHIP PAD
			DESIGN
26.	20070230130	10/4/2007	ADJUSTABLE THICKNESS
	11396711	4/4/2006	THERMAL INTERPOSER
			AND ELECTRONIC
			PACKAGE UTILIZING
	00070001404	0/07/0007	SAME
27.	20070221404	9/27/2007	CIRCUITIZED SUBSTRATE AND CONDUCTIVE PASTE,
	11802434	5/23/2007	ELECTRICAL ASSEMBLY
			INCLUDING SAID
			CIRCUITIZED SUBSTRATE
			AND METHOD OF MAKING
			SAID SUBSTRATE
28.	20070199195	8/30/2007	METHOD FOR MAKING A
20.	11797232	5/2/2007	MULTILAYERED
	1.1,7,1232		CIRCUITIZED SUBSTRATE
29.	20070177331	8/2/2007	NON-FLAKING CAPACITOR
۵,	11730761	4/4/2007	MATERIAL, CAPACITIVE
	11750701		SUBSTRATE HAVING AN
L	1		

	PATENT NO./	DATE	
NO.	PUBLICATION NO.	ISSUED/	TITLE
	SERIAL NO.	DATE FILED	
			INTERNAL CAPACITOR
			THEREIN INCLUDING SAID
			NON-FLAKING CAPACITOR
			MATERIAL, AND METHOD
			OF MAKING A CAPACITOR
			MEMBER FOR USE IN A
			CAPACITIVE SUBSTRATE
30.	20070139977	6/21/2007	METHOD OF IMPROVING
	11305073	12/19/2005	ELECTRICAL
			CONNECTIONS IN
			CIRCUITIZED SUBSTRATES
31.	20070090170	4/26/2007	METHOD OF MAKING A
	11253659	10/20/2005	CIRCUITIZED SUBSTRATE
			HAVING A PLURALITY OF
			SOLDER CONNECTION
			SITES THEREON
32.	20070089290	4/26/2007	METHOD OF MAKING A
	11634287	12/6/2006	PRINTED CIRCUIT BOARD
			WITH LOW CROSS-TALK
			NOISE
33.	20070075726	4/5/2007	INTERPOSER AND TEST
	11607973	12/4/2006	ASSEMBLY FOR TESTING
			ELECTRONIC DEVICES
34.	20070010065	1/11/2007	METHOD OF MAKING A
	11352279	2/13/2006	CAPACITIVE SUBSTRATE
			FOR USE AS PART OF A
			LARGER CIRCUITIZED
			SUBSTRATE, METHOD OF
			MAKING SAID
			CIRCUITIZED SUBSTRATE
			AND METHOD OF MAKING
			AN INFORMATION
			HANDLING SYSTEM
			INCLUDING SAID
			CIRCUITIZED SUBSTRATE
35.	20070010064	1/11/2007	METHOD OF MAKING A
1	11352276	2/13/2006	CAPACITIVE SUBSTRATE
			USING PHOTOIMAGEABLE
1			DIELECTRIC FOR USE AS
			PART OF A LARGER
			CIRCUITIZED SUBSTRATE,
			METHOD OF MAKING SAID
			CIRCUITIZED SUBSTRATE
			AND METHOD OF MAKING
			AN INFORMATION
			HANDLING SYSTEM
			INCLUDING SAID
126	20070007022	1/11/2007	CIRCUITIZED SUBSTRATE
36.	20070007033	1/11/2007	CIRCUITIZED SUBSTRATE
	11244180	10/6/2005	WITH SOLER-COATED
			MICROPARTICLE PASTE

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NO.   PUBLICATION NO.   DATE FILED   CONNECTIONS, MULTI-LAYERED SUBSTRATE   ASSEMBLY, ELECTRICAL   ASSEMBLY, ELECTRICAL   ASSEMBLY, ELECTRICAL   ASSEMBLY, AND   INFORMATION HANDLING   SYSTEM UTILIZING SAME   AND METHOD OF MAKING   SAID SUBSTRATE	4 minute (1945)		Angel de la	
SERIAL NO.   DATE FILED		PATENT NO./	DATE	POWNED TO
CONNECTIONS, MULTI- LAYERED SUBSTRATE   ASSEMBLY, ELECTRICAL     ASSEMBLY AND     INFORMATION HANDLING     SYSTEM UTILIZING SAME     AND METHOD OF MAKING     SAID SUBSTRATE     AND SUBSTRATE     AND METHOD OF MAKING     CIRCUITIZED SUBSTRATE     WITH FILLED ISOLATION     BORDER     STACKED CHIP     ELECTRONIC PACKAGE     HAVING LAMINATE     CARRIER     APPARATUS AND METHOD     SUBSTRATES HAVING     PHOTO-IMAGEABLE     DIELECTRIC LAYERS IN A     CONTINUOUS MANNER     CIRCUITIZED SUBSTRATE     CONTINUOUS MANNER     CONTINUOUS MANNER     CIRCUITIZED SUBSTRATE     CIRCUITIZED SUBSTRATE     CIRCUITIZED SUBSTRATE     CONTINUOUS MANNER     CONTINUOUS MANNER     CIRCUITIZED SUBSTRATE     CONTINUOUS MANNER     CONTINUOUS MANNER     CONTINUOUS MANNER     CONTINUOUS MANNER     CONTINUOUS MANNER	I NO		A CONTRACTOR OF THE PROPERTY O	
LAYERED SUBSTRATE   ASSEMBLY, ELECTRICAL   ASSEMBLY AND   INFORMATION HANDLING   SYSTEM UTILIZING SAME   AND METHOD OF MAKING   SAID SUBSTRATE   METHOD OF MAKING   CIRCUITIZED SUBSTRATE   WITH FILLED ISOLATION   BORDER	is si i	SENIME AV.		CONNECTIONS MILITI-
ASSEMBLY, ELECTRICAL   ASSEMBLY AND   INFORMATION HANDLING   SYSTEM UTILIZING SAME   AND METHOD OF MAKING   SAID SUBSTRATE				
ASSEMBLY AND   INFORMATION HANDLING   SYSTEM UTILIZING SAME   AND METHOD OF MAKING   SAID SUBSTRATE				
INFORMATION HANDLING   SYSTEM UTILIZING SAME   AND METHOD OF MAKING   SAID SUBSTRATE				· · · · · · · · · · · · · · · · · · ·
SYSTEM UTILIZING SAME   AND METHOD OF MAKING   SAID SUBSTRATE				
AND METHOD OF MAKING				
SAID SUBSTRATE				- ·
37.   20060248717   11/9/2006   METHOD OF MAKING   CIRCUITIZED SUBSTRATE   WITH FILLED ISOLATION   BORDER     38.   20060240594   10/26/2006   METHOD OF MAKING   STACKED CHIP   ELECTRONIC PACKAGE   HAVING LAMINATE   CARRIER     39.   20060240364   10/26/2006   APPARATUS AND METHOD   FOR MAKING CIRCUITIZED   SUBSTRATES HAVING   PHOTO-IMAGEABLE   DIELECTRIC LAYERS IN A   CONTINUOUS MANNER     40.   20060214010   9/28/2006   CIRCUITIZED SUBSTRATE   AVING   PHOTO-IMAGEABLE   DIELECTRIC LAYERS IN A   CONTINUOUS MANNER     40.   20060214010   4/11/2006   WITH SHIELDED SIGNAL   LINES AND PLATED-THRUHOLES AND METHOD OF   MAKING SAME, AND   ELECTRICAL ASSEMBLY				1
11482945   7/10/2006   CIRCUITIZED SUBSTRATE WITH FILLED ISOLATION BORDER     38.   20060240594   10/26/2006   METHOD OF MAKING STACKED CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER     39.   20060240364   10/26/2006   APPARATUS AND METHOD SUBSTRATES HAVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER     40.   20060214010   9/28/2006   CIRCUITIZED SUBSTRATE   AVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER     40.   20060214010   4/11/2006   WITH SHIELDED SIGNAL LINES AND PLATED-THRUHOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY	37.	20060248717	11/9/2006	METHOD OF MAKING
WITH FILLED ISOLATION BORDER   38.   20060240594   10/26/2006   METHOD OF MAKING STACKED CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER   39.   20060240364   10/26/2006   APPARATUS AND METHOD FOR MAKING CIRCUITIZED SUBSTRATES HAVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER   40.   20060214010   9/28/2006   CIRCUITIZED SUBSTRATE   WITH SHIELDED SIGNAL LINES AND PLATED-THRUHOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY			7/10/2006	CIRCUITIZED SUBSTRATE
38.   20060240594   10/26/2006   METHOD OF MAKING   STACKED CHIP   ELECTRONIC PACKAGE   HAVING LAMINATE   CARRIER     39.   20060240364   10/26/2006   APPARATUS AND METHOD   FOR MAKING CIRCUITIZED   SUBSTRATES HAVING   PHOTO-IMAGEABLE   DIELECTRIC LAYERS IN A   CONTINUOUS MANNER     40.   20060214010   9/28/2006   CIRCUITIZED SUBSTRATE   WITH SHIELDED SIGNAL   LINES AND PLATED-THRUHOLES AND METHOD OF   MAKING SAME, AND   ELECTRICAL ASSEMBLY				WITH FILLED ISOLATION
11455183 6/19/2006 STACKED CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER  39. 20060240364 11110920 4/21/2005 FOR MAKING CIRCUITIZED SUBSTRATES HAVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER  40. 20060214010 11401401 9/28/2006 CIRCUITIZED SUBSTRATE WITH SHIELDED SIGNAL LINES AND PLATED-THRU- HOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY				BORDER
11455183   6/19/2006   STACKED CHIP   ELECTRONIC PACKAGE   HAVING LAMINATE   CARRIER     39.   20060240364   10/26/2006   APPARATUS AND METHOD   FOR MAKING CIRCUITIZED   SUBSTRATES HAVING   PHOTO-IMAGEABLE   DIELECTRIC LAYERS IN A   CONTINUOUS MANNER     40.   20060214010   9/28/2006   CIRCUITIZED SUBSTRATE   WITH SHIELDED SIGNAL   LINES AND PLATED-THRUHOLES AND METHOD OF   MAKING SAME, AND   ELECTRICAL ASSEMBLY	38.	20060240594	10/26/2006	METHOD OF MAKING
HAVING LAMINATE CARRIER  39. 20060240364 10/26/2006 APPARATUS AND METHOD 11110920 4/21/2005 FOR MAKING CIRCUITIZED SUBSTRATES HAVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER  40. 20060214010 9/28/2006 CIRCUITIZED SUBSTRATE 11401401 4/11/2006 WITH SHIELDED SIGNAL LINES AND PLATED-THRU- HOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY		t i	6/19/2006	STACKED CHIP
39. 20060240364 10/26/2006 APPARATUS AND METHOD FOR MAKING CIRCUITIZED SUBSTRATES HAVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER  40. 20060214010 9/28/2006 CIRCUITIZED SUBSTRATE WITH SHIELDED SIGNAL LINES AND PLATED-THRUHOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY				ELECTRONIC PACKAGE
39. 20060240364 10/26/2006 APPARATUS AND METHOD FOR MAKING CIRCUITIZED SUBSTRATES HAVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER  40. 20060214010 9/28/2006 CIRCUITIZED SUBSTRATE WITH SHIELDED SIGNAL LINES AND PLATED-THRUHOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY				HAVING LAMINATE
11110920  4/21/2005  FOR MAKING CIRCUITIZED SUBSTRATES HAVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER  40. 20060214010 11401401  9/28/2006 CIRCUITIZED SUBSTRATE WITH SHIELDED SIGNAL LINES AND PLATED-THRUHOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY				CARRIER
SUBSTRATES HAVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER  40. 20060214010 9/28/2006 CIRCUITIZED SUBSTRATE 11401401 4/11/2006 WITH SHIELDED SIGNAL LINES AND PLATED-THRU- HOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY	39.	20060240364	10/26/2006	APPARATUS AND METHOD
PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER  40. 20060214010 9/28/2006 CIRCUITIZED SUBSTRATE 11401401 4/11/2006 WITH SHIELDED SIGNAL LINES AND PLATED-THRU- HOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY		11110920	4/21/2005	FOR MAKING CIRCUITIZED
DIELECTRIC LAYERS IN A CONTINUOUS MANNER  40. 20060214010 9/28/2006 CIRCUITIZED SUBSTRATE 11401401 4/11/2006 WITH SHIELDED SIGNAL LINES AND PLATED-THRU- HOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY				SUBSTRATES HAVING
40. 20060214010 9/28/2006 CIRCUITIZED SUBSTRATE 11401401 4/11/2006 WITH SHIELDED SIGNAL LINES AND PLATED-THRU- HOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY	İ			PHOTO-IMAGEABLE
40. 20060214010 9/28/2006 CIRCUITIZED SUBSTRATE 11401401 4/11/2006 WITH SHIELDED SIGNAL LINES AND PLATED-THRU- HOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY		:		1
11401401  4/11/2006  WITH SHIELDED SIGNAL LINES AND PLATED-THRU-HOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY				
LINES AND PLATED-THRU- HOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY	40.	20060214010	9/28/2006	4
HOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY		11401401	4/11/2006	
MAKING SAME, AND ELECTRICAL ASSEMBLY				
ELECTRICAL ASSEMBLY				
AND INFORMATION				
HANDLING SYSTEM				
UTILIZING SAME				
41. 20060213973 9/28/2006 ELECTRONIC CARD	41.			
11086324 3/23/2005 ASSEMBLY				
42. 20060200977 9/14/2006 METHOD OF MAKING	42.	1	*/ 1 <b>= 0 0 0</b>	
11429990 5/9/2006 CIRCUITIZED SUBSTRATE		11429990	3/9/2006	
WITH SIGNAL WIRE				
SHIELDING   SHIELDING   43.   20060180936   8/17/2006   FLUOROPOLYMER	12	20060180026	8/17/2006	
43.   20060180936   8/17/2006   FLUOROPOLYMER   11390386   3/28/2006   DIELECTRIC	43.			
11390380 3/28/2000 DIEEECTRIC COMPOSITION FOR USE IN		11390360	3/26/2000	
				CIRCUITIZED SUBSTRATES
AND CIRCUITIZED				Į.
SUBSTRATE INCLUDING				1
SAME	1			1
44. 20060180343 8/17/2006 CIRCUITIZED SUBSTRATE	44	20060180343	8/17/2006	<u> </u>
11215206 8/31/2005 UTILIZING THREE			i	
SMOOTH-SIDED				
CONDUCTIVE LAYERS AS				
PART THEREOF AND				
ELECTRICAL ASSEMBLIES	1			

F. Yas	PATENT NO.	DATE	
NO.	PUBLICATION NO./	ISSUED/	TITLE
417	SERIAL NO.	DATE FILED	
			AND INFORMATION
			HANDLING SYSTEMS
	<u> </u>		UTILIZING SAME
45.	20060154501	7/13/2006	CAPACITOR MATERIAL
ļ	11324273	1/4/2006	WITH METAL COMPONENT
1			FOR USE IN CIRCUITIZED
			SUBSTRATES,
			CIRCUITIZED SUBSTRATE
E .			UTILIZING SAME, METHOD
			OF MAKING SAID
			CIRCUITIZED SUBSTRATE,
			AND INFORMATION HANDLING SYSTEM
			UTILIZING SAID
			CIRCUITIZED SUBSTRATE
12	200(01519(2	7/13/2006	CAPACITOR MATERIAL
46.	20060151863	1/10/2005	FOR USE IN CIRCUITIZED
	11031085	1/10/2003	SUBSTRATES,
			CIRCUITIZED SUBSTRATE
			UTILIZING SAME, METHOD
			OF MAKING SAID
			CIRCUITIZED SUBSTRATE,
			AND INFORMATION
			HANDLING SYSTEM
			UTILIZING SAID
			CIRCUITIZED SUBSTRATE
47.	20060125103	6/15/2006	INFORMATION HANDLING
'''	11350777	2/10/2006	SYSTEM
48.	20060121722	6/8/2006	METHOD OF MAKING
	11334445	1/19/2006	PRINTED CIRCUIT BOARD
			HAVING VARYING DEPTH
			CONDUCTIVE HOLES
49.	20060054870	3/16/2006	DIELECTRIC
	11265287	11/3/2005	COMPOSITION FOR USE IN
			CIRCUITIZED SUBSTRATES
			AND CIRCUITIZED
			SUBSTRATE INCLUDING
		10/00/0005	SAME METHOD AND SYSTEM
50.	20050289019	12/29/2005 6/4/2004	FOR TRACKING GOODS
<i>E</i> 1	10860067 20050218524	10/6/2005	LOW MOISTURE
51.	11086323	3/23/2005	ABSORPTIVE CIRCUITIZED
	11000323	314312003	SUBSTRATE WITH
			REDUCED THERMAL
			EXPANSION, METHOD OF
			MAKING SAME,
			ELECTRICAL ASSEMBLY
			UTILIZING SAME, AND
			INFORMATION HANDLING
			SYSTEM UTILIZING SAME
		•	

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370	PATENT NO./ PUBLICATION NO./	DATE ISSUED/	TEMLE:
NO.	SERIAL NO.	DATE FILED	
52.	20050137890	6/23/2005	ITEM IDENTIFICATION
32.	10740500	12/22/2003	AND CONTROL SYSTEM
<u> </u>	20040242270	12/2/2004	ELECTRONIC CARD
53.	10449019	6/2/2003	ELECTRONIC CARD
54.	20040238970	12/2/2004	ELECTRONIC PACKAGE
34.	10868066	6/16/2004	WITH CONDUCTIVE PAD
	10000000	0/10/2004	CAPABLE OF
			WITHSTANDING
			SIGNIFICANT LOADS
55.	7416996	8/26/2008	METHOD OF MAKING
33.	11349990	2/9/2006	CIRCUITIZED SUBSTRATE
56.	7416972	8/26/2008	METHOD OF MAKING
50.	11730942	4/5/2007	SAME LOW MOISTURE
	11750742	4/5/2007	ABSORPTIVE CIRCUITIZED
			SUBSTRATE WITH
			REDUCED THERMAL
			EXPANSION
57.	7384856	6/10/2008	METHOD OF MAKING AN
57.	11172794	7/5/2005	INTERNAL CAPACITIVE
	11172774	71572003	SUBSTRATE FOR USE IN A
			CIRCUITIZED SUBSTRATE
			AND METHOD OF MAKING
			SAID CIRCUITIZED
			SUBSTRATE
58.	7383629	6/10/2008	METHOD OF MAKING
50.	10991532	11/19/2004	CIRCUITIZED SUBSTRATES
			UTILIZING SMOOTH-SIDED
			CONDUCTIVE LAYERS AS
			PART THEREOF
59.	7381587	6/3/2008	METHOD OF MAKING
1	11324432	1/4/2006	CIRCUITIZED SUBSTRATE
60.	7377033	5/27/2008	METHOD OF MAKING
	11641810	12/20/2006	CIRCUITIZED SUBSTRATE
			WITH SPLIT CONDUCTIVE
			LAYER AND
			INFORMATION HANDLING
			SYSTEM UTILIZING SAME
61.	7348677	3/25/2008	METHOD OF PROVIDING
	11397713	4/5/2006	PRINTED CIRCUIT BOARD
			WITH CONDUCTIVE HOLES
			AND BOARD RESULTING
			THEREFROM
62.	7343674	3/18/2008	METHOD OF MAKING
	11349998	2/9/2006	CIRCUITIZED SUBSTRATE
			ASSEMBLY
63.	7342183	3/11/2008	CIRCUITIZED SUBSTRATE
	11177442	7/11/2005	WITH SINTERED PASTE
			CONNECTIONS,
			MULTILAYERED
			SUBSTRATE ASSEMBLY,
L			ELECTRICAL ASSEMBLY

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NO.	PUBLICATION NO.	X304 (000 000 000 000 000 000 000 000 000	TITLE
l'iti	SERIAL NO.	DATE FILED	
			AND INFORMATION
			HANDLING SYSTEM
			UTILIZING SAME
64.	7334323	2/26/2008	METHOD OF MAKING
0 1.	11177413	7/11/2005	MULTILAYERED
	1117,113	,,,	CIRCUITIZED SUBSTRATE
			ASSEMBLY HAVING
			SINTERED PASTE
1			CONNECTIONS
65.	7332818	2/19/2008	MULTI-CHIP ELECTRONIC
05.	11127160	5/12/2005	PACKAGE WITH REDUCED
		J. 10.	LINE SKEW AND
			CIRCUITIZED SUBSTRATE
			FOR USE THEREON
66.	7332212	2/19/2008	CIRCUITIZED SUBSTRATE
-0.	11242841	10/5/2005	WITH CONDUCTIVE
			POLYMER AND SEED
			MATERIAL ADHESION
			LAYER
67.	7328502	2/12/2008	APPARATUS FOR MAKING
•,.	11882625	8/3/2007	CIRCUITIZED SUBSTRATES
			IN A CONTINUOUS
			MANNER
68.	7326643	2/5/2008	METHOD OF MAKING
	11808596	6/12/2007	CIRCUITIZED SUBSTRATE
			WITH INTERNAL ORGANIC
			MEMORY DEVICE
69.	7307022	12/11/2007	METHOD OF TREATING
	11327493	1/9/2006	CONDUCTIVE LAYER FOR
			USE IN A CIRCUITIZED
			SUBSTRATE AND METHOD
			OF MAKING SAID
			SUBSTRATE HAVING SAID
İ			CONDUCTIVE LAYER AS
			PART THEREOF
70.	7294791	11/13/2007	CIRCUITIZED SUBSTRATE
	10953923	9/29/2004	WITH IMPROVED
			IMPEDANCE CONTROL
			CIRCUITRY, METHOD OF
			MAKING SAME,
			ELECTRICAL ASSEMBLY
			AND INFORMATION
			HANDLING SYSTEM
		4445:555	UTILIZING SAME
71.	7293355	11/13/2007	APPARATUS AND METHOD
	11110919	4/21/2005	FOR MAKING CIRCUITIZED
			SUBSTRATES IN A
		1116/060=	CONTINUOUS MANNER
72.	7292055	11/6/2007	INTERPOSER FOR USE
	11110901	4/21/2005	WITH TEST APPARATUS
73.	7270845	9/18/2007	DIELECTRIC

10.42	PRODUCTION OF THE PROPERTY OF		
310	PATENT NO./	DATE	TITLE:
NO.	PUBLICATION NO./ SERIAL NO.	ISSUED/ DATE FILED	
		3/31/2004	COMPOSITION FOR
	10812889	3/31/2004	FORMING DIELECTRIC
			LAYER FOR USE IN
	00.50.51.0	0/7/2007	CIRCUITIZED SUBSTRATES
74.	7253518	8/7/2007	WIREBOND ELECTRONIC
1	11152048	6/15/2005	PACKAGE WITH
			ENHANCED CHIP PAD DESIGN, METHOD OF
			MAKING SAME, AND
1			INFORMATION HANDLING
<del></del>	50.50.500	0/7/0007	SYSTEM UTILIZING SAME
75.	7253502	8/7/2007	CIRCUITIZED SUBSTRATE
	10900385	7/28/2004	WITH INTERNAL ORGANIC
			MEMORY DEVICE,
			ELECTRICAL ASSEMBLY
			UTILIZING SAME, AND
			INFORMATION HANDLING
		6/06/0005	SYSTEM UTILIZING SAME
76.	7235745	6/26/2007	RESISTOR MATERIAL
	11172786	7/5/2005	WITH METAL COMPONENT
			FOR USE IN CIRCUITIZED
			SUBSTRATES,
			CIRCUITIZED SUBSTRATE
			UTILIZING SAME, METHOD
			OF MAKING SAID
			CIRCUITIZED SUBSTRATE,
			AND INFORMATION
			HANDLING SYSTEM
			UTILIZING SAID
		- / · / · · · · · · · · · · · · · · · ·	CIRCUITIZED SUBSTRATE
77.	7211470	5/1/2007	METHOD AND APPARATUS
	11216133	9/1/2005	FOR DEPOSITING
			CONDUCTIVE PASTE IN
			CIRCUITIZED SUBSTRATE
	7011000	5/1/2007	OPENINGS
78.	7211289	5/1/2007	METHOD OF MAKING
1	10737974	12/18/2003	MULTILAYERED PRINTED
			CIRCUIT BOARD WITH
			FILLED CONDUCTIVE
70	7200269	4/24/2007	HOLES
79.	7209368	4/24/2007	CIRCUITIZED SUBSTRATE
	10790747	3/3/2004	WITH SIGNAL WIRE
			SHIELDING, ELECTRICAL ASSEMBLY UTILIZING
			SAME AND METHOD OF
			MAKING
00	7176202	2/13/2007	PRINTED CIRCUIT BOARD
80.	7176383 10740398	12/22/2003	WITH LOW CROSS-TALK
	10/40398	12/22/2003	NOISE
01	7160212	1/30/2007	PLATING METHOD FOR
81.	7169313		
	11128272	5/13/2005	CIRCUITIZED SUBSTRATES

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1 1000000	PATENT NO./	DATE	
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02	7163847	1/16/2007	METHOD OF MAKING
82.	11258092	10/26/2005	CIRCUITIZED SUBSTRATE
83.	7161810	1/9/2007	STACKED CHIP
83.	11238960	9/30/2005	ELECTRONIC PACKAGE
	11230900	9/30/2003	HAVING LAMINATE
			CARRIER AND METHOD OF
			MAKING SAME
84.	7157647	1/2/2007	CIRCUITIZED SUBSTRATE
04.	10882170	7/2/2004	WITH FILLED ISOLATION
	10002170	1/2/2004	BORDER, METHOD OF
			MAKING SAME,
			ELECTRICAL ASSEMBLY
			UTILIZING SAME, AND
			INFORMATION HANDLING
			SYSTEM UTILIZING SAME
85.	7157646	1/2/2007	CIRCUITIZED SUBSTRATE
65.	10882167	7/2/2004	WITH SPLIT CONDUCTIVE
	10002107	77272001	LAYER, METHOD OF
			MAKING SAME,
			ELECTRICAL ASSEMBLY
			UTILIZING SAME, AND
			INFORMATION HANDLING
			SYSTEM UTILIZING SAME
86.	7152319	12/26/2006	METHOD OF MAKING
	10811817	3/30/2004	HIGH SPEED CIRCUIT
			BOARD
87.	7145221	12/5/2006	LOW MOISTURE
İ	10920235	8/18/2004	ABSORPTIVE CIRCUITIZED
			SUBSTRATE, METHOD OF
			MAKING SAME,
			ELECTRICAL ASSEMBLY
			UTILIZING SAME, AND
			INFORMATION HANDLING
			SYSTEM UTILIZING SAME
88.	7142121	11/28/2006	RADIO FREQUENCY
	10860071	6/4/2004	DEVICE FOR TRACKING
			GOODS
89.	7129732	10/31/2006	SUBSTRATE TEST
	11281456	11/18/2005	APPARATUS AND METHOD
			OF TESTING SUBSTRATES
90.	7109732	9/19/2006	ELECTRONIC COMPONENT
	10630722	7/31/2003	TEST APPARATUS
91.	7091066	8/15/2006	METHOD OF MAKING
	11259043	10/27/2005	CIRCUITIZED SUBSTRATE
92.	7087846	8/8/2006	PINNED ELECTRONIC
	10423972	4/28/2003	PACKAGE WITH
			STRENGTHENED
		0 /0 /5 0 0	CONDUCTIVE PAD
93.	7087441	8/8/2006	METHOD OF MAKING A
	10968929	10/21/2004	CIRCUITIZED SUBSTRATE
			HAVING A PLURALITY OF

-7 a 4	PATENT NO.	DATE	
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······			SOLDER CONNECTION
			SITES THEREON
94.	7084014	8/1/2006	METHOD OF MAKING
	10679302	10/7/2003	CIRCUITIZED SUBSTRATE
95.	7078816	7/18/2006	CIRCUITIZED SUBSTRATE
	10812890	3/31/2004	
96.	7071423	7/4/2006	CIRCUITIZED SUBSTRATE
	10915483	8/11/2004	ASSEMBLY AND METHOD
			OF MAKING SAME
97.	7063762	6/20/2006	CIRCUITIZED SUBSTRATE
	10643909	8/20/2003	AND METHOD OF MAKING
			SAME
98.	7047630	5/23/2006	METHOD OF MAKING
	10811915	3/30/2004	CIRCUITIZED SUBSTRATE
			ASSEMBLY
99.	7045897	5/16/2006	ELECTRICAL ASSEMBLY
1	10900386	7/28/2004	WITH INTERNAL MEMORY
j			CIRCUITIZED SUBSTRATE
1			HAVING ELECTRONIC
			COMPONENTS
			POSITIONED THEREON,
			METHOD OF MAKING
			SAME, AND INFORMATION
			HANDLING SYSTEM
		4/0-7/0-0-0-5	UTILIZING SAME
100.	7035113	4/25/2006	MULTI-CHIP ELECTRONIC
	10394107	3/24/2003	PACKAGE HAVING
			LAMINATE CARRIER AND
	,		METHOD OF MAKING SAME
101.	7025607	4/11/2006	CAPACITOR MATERIAL
101.	11031074	1/10/2005	WITH METAL COMPONENT
	11031074	1/10/2003	FOR USE IN CIRCUITIZED
			SUBSTRATES,
			CIRCUITIZED SUBSTRATE
			UTILIZING SAME, METHOD
] .			OF MAKING SAID
			CIRCUITIZED SUBSTRATE,
			AND INFORMATION
			HANDLING SYSTEM
			UTILIZING SAID
			CIRCUITIZED SUBSTRATE
102.	7023707	4/4/2006	INFORMATION HANDLING
	10394135	3/24/2003	SYSTEM
103.	7013563	3/21/2006	METHOD OF TESTING
	10616932	7/11/2003	SPACINGS IN PATTERNS
			OF OPENINGS IN PCB
			CONDUCTIVE LAYER
104.	6995322	2/7/2006	HIGH SPEED CIRCUITIZED
	10955741	9/30/2004	SUBSTRATE WITH
			REDUCED THRU-HOLE

PATENT'NO./   SUBJUED   SUBJUED   STUB, METHOD FOR FABRICATION AND INFORMATION HANDL SYSTEM UTILIZING SAME   105.   6992896   1/31/2006   5TACKED CHIP   ELECTRONIC PACKAGI   HAVING LAMINATE   CARRIER AND METHOD   MAKING SAME   10991451   11/19/2004   UTILIZING THREE   SMOOTH-SIDED   CONDUCTIVE LAYERS   PART THEREOF, METHOOF MAKING SAME, AND INFORMATION   HANDLING SYSTEMS   UTILIZING SAME   AND INFORMATION   HANDLING SYSTEMS   UTILIZING SAME   10409066   4/9/2003   TO FORM SEGMENTED   PRODUCT   108.   6905589   6/14/2005   CIRCUITIZED SUBSTRAID   10370529   2/24/2003   AND METHOD OF MAK   SAME   109.   6900392   10933260   9/3/2004   SYSTEM UTILIZING SUBSTRAID   100.   6872894   3/29/2005   INFORMATION HANDL   SYSTEM UTILIZING SUBSTRAID   10379575   3/6/2003   SYSTEM UTILIZING SYSTEM UTILIZING   SYS	ME  D OF  TES  AS  OD  D  LIES
SERIAL NO.   DATE FILED	ME  D OF  TES  AS  OD  D  LIES
STUB, METHOD FOR FABRICATION AND INFORMATION HANDL SYSTEM UTILIZING SA	ME  D OF  TES  AS  OD  D  LIES
FABRICATION AND   INFORMATION HANDL   SYSTEM UTILIZING SA	ME  D OF  TES  AS  OD  D  LIES
INFORMATION HANDL   SYSTEM UTILIZING SA	ME  D OF  TES  AS  OD  D  LIES
SYSTEM UTILIZING SA	ME  D OF  TES  AS  OD  D  LIES
105.   6992896   1/31/2006   STACKED CHIP   10661616   9/15/2003   ELECTRONIC PACKAGI   HAVING LAMINATE   CARRIER AND METHOD   MAKING SAME   10991451   11/19/2004   UTILIZING THREE   SMOOTH-SIDED   CONDUCTIVE LAYERS   PART THEREOF, METHOD   OF MAKING SAME   AND INFORMATION   HANDLING SYSTEMS   UTILIZING SAME   AND INFORMATION   HANDLING SYSTEMS   UTILIZING SAME   10409066   4/9/2003   TO FORM SEGMENTED   PRODUCT   108.   6905589   6/14/2005   CIRCUITIZED SUBSTRAE   10370529   2/24/2003   AND METHOD OF MAK   SAME   109.   6900392   5/31/2005   INFORMATION   HANDLE   10933260   9/3/2004   SYSTEM UTILIZING   CIRCUITIZED SUBSTRAE   110.   6872894   3/29/2005   INFORMATION   HANDLE   1090000000000000000000000000000000000	O OF TES AS OD O
10661616   9/15/2003   ELECTRONIC PACKAGI	AS OD O LIES
HAVING LAMINATE   CARRIER AND METHOR   MAKING SAME	AS OD O LIES
CARRIER AND METHOR   MAKING SAME	AS OD O JIES
MAKING SAME   106. 6964884	AS OD O JIES
106.   6964884   11/15/2005   CIRCUITIZED SUBSTRA   10991451   11/19/2004   UTILIZING THREE   SMOOTH-SIDED   CONDUCTIVE LAYERS   PART THEREOF, METHOOF MAKING SAME, AND INFORMATION   HANDLING SYSTEMS   UTILIZING SAME   107.   6958106   10/25/2005   MATERIAL SEPARATION   10409066   4/9/2003   TO FORM SEGMENTED   PRODUCT   108.   6905589   6/14/2005   CIRCUITIZED SUBSTRA   10370529   2/24/2003   AND METHOD OF MAK   SAME   109.   6900392   5/31/2005   INFORMATION HANDL   10933260   9/3/2004   SYSTEM UTILIZING   CIRCUITIZED SUBSTRA   110.   6872894   3/29/2005   INFORMATION HANDL   110.   10/25/2005   INFORMATION HANDL   110/25/2005   INFORMATION HANDL   110/25/2005   INFORMATION HANDL   110/25/2005   INFORMATION HANDL   110/25/2005   11	AS OD O JIES
10991451	AS OD O JIES
SMOOTH-SIDED   CONDUCTIVE LAYERS   PART THEREOF, METHOR   OF MAKING SAME, AND ELECTRICAL ASSEMBLE   AND INFORMATION   HANDLING SYSTEMS   UTILIZING SAME	OD JES
CONDUCTIVE LAYERS   PART THEREOF, METHOR   OF MAKING SAME, AND ELECTRICAL ASSEMBLE   AND INFORMATION   HANDLING SYSTEMS   UTILIZING SAME   UTILIZING SEGMENTED   PRODUCT   UTILIZING   CIRCUITIZED SUBSTRATION   SAME   UTILIZING   UTILI	OD JES
PART THEREOF, METHO OF MAKING SAME, AND ELECTRICAL ASSEMBLE AND INFORMATION HANDLING SYSTEMS UTILIZING SAME	OD JES
OF MAKING SAME, AND ELECTRICAL ASSEMBLE AND INFORMATION HANDLING SYSTEMS UTILIZING SAME   107.   6958106   10/25/2005   MATERIAL SEPARATION TO FORM SEGMENTED PRODUCT   108.   6905589   6/14/2005   CIRCUITIZED SUBSTRATION SAME   10370529   2/24/2003   AND METHOD OF MAK SAME   109.   6900392   5/31/2005   INFORMATION HANDLE 10933260   9/3/2004   SYSTEM UTILIZING CIRCUITIZED SUBSTRATION GRAPH   110.   6872894   3/29/2005   INFORMATION HANDLE   109.   109	D JES
ELECTRICAL ASSEMBL   AND INFORMATION   HANDLING SYSTEMS   UTILIZING SAME   107.   6958106   10/25/2005   MATERIAL SEPARATION   TO FORM SEGMENTED   PRODUCT   108.   6905589   6/14/2005   CIRCUITIZED SUBSTRATION   10370529   2/24/2003   AND METHOD OF MAK   SAME   109.   6900392   5/31/2005   INFORMATION HANDL   10933260   9/3/2004   SYSTEM UTILIZING   CIRCUITIZED SUBSTRATION   6872894   3/29/2005   INFORMATION HANDL	IES
AND INFORMATION HANDLING SYSTEMS UTILIZING SAME  107. 6958106 10/25/2005 MATERIAL SEPARATIO 10409066 4/9/2003 TO FORM SEGMENTED PRODUCT  108. 6905589 6/14/2005 CIRCUITIZED SUBSTRA 10370529 2/24/2003 AND METHOD OF MAK SAME  109. 6900392 5/31/2005 INFORMATION HANDL 10933260 9/3/2004 SYSTEM UTILIZING CIRCUITIZED SUBSTRA 110. 6872894 3/29/2005 INFORMATION HANDL	
HANDLING SYSTEMS UTILIZING SAME	N
UTILIZING SAME	N
107.         6958106         10/25/2005         MATERIAL SEPARATION           10409066         4/9/2003         TO FORM SEGMENTED PRODUCT           108.         6905589         6/14/2005         CIRCUITIZED SUBSTRATION AND METHOD OF MAK SAME           109.         6900392         5/31/2005         INFORMATION HANDL SYSTEM UTILIZING CIRCUITIZED SUBSTRATION           110.         6872894         3/29/2005         INFORMATION HANDL	NI
10409066	I N
PRODUCT	
108.         6905589         6/14/2005         CIRCUITIZED SUBSTRA AND METHOD OF MAK SAME           109.         6900392         5/31/2005         INFORMATION HANDL SYSTEM UTILIZING CIRCUITIZED SUBSTRA CIRCUITIZED SUBSTRA SILVED SUBS	
10370529   2/24/2003   AND METHOD OF MAK SAME   109.   6900392   5/31/2005   INFORMATION HANDL SYSTEM UTILIZING CIRCUITIZED SUBSTRATIO.   6872894   3/29/2005   INFORMATION HANDL	TE
SAME   109.   6900392   5/31/2005   INFORMATION HANDL   10933260   9/3/2004   SYSTEM UTILIZING   CIRCUITIZED SUBSTRA   110.   6872894   3/29/2005   INFORMATION HANDL	
10933260   9/3/2004   SYSTEM UTILIZING   CIRCUITIZED SUBSTRA   110.   6872894   3/29/2005   INFORMATION HANDL	
10933260   9/3/2004   SYSTEM UTILIZING   CIRCUITIZED SUBSTRA   110.   6872894   3/29/2005   INFORMATION HANDL	NG
110. 6872894 3/29/2005 INFORMATION HANDL	TE
	NG
CIRCUITIZED SUBSTRA	TE
111. 6828514 12/7/2004 HIGH SPEED CIRCUIT	
10354000 1/30/2003 BOARD AND METHOD	FOR
FABRICATION	
112. 6815837 11/9/2004 ELECTRONIC PACKAGI	3
10423877   4/28/2003   WITH STRENGTHENED	
CONDUCTIVE PAD	
113. 6809269 10/26/2004 CIRCUITIZED SUBSTRA	TE
10322527   12/19/2002   ASSEMBLY AND METH	OD
OF MAKING SAME	
114. 11907006 10/9/2007 PCB WITH OPTICAL	
PATHWAYS	
115. 11907004 10/9/2007 PCB WITH OPTICAL	
PATHWAYS	
116. 11976468 10/25/2007 IC/PACKAGE WITH	
THERMAL COOLING	
STRUCTURE	
117.   12007820   1/16/2008   STRUCTURE AND METI	
FOR HIGH-SPEED	HOD
PRECISION RESISTOR	HOD

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NO.	PUBLICATION NO./ SERIAL NO.	ISSUED/ DATE FILED	TITLE:
16/2000			FORMATION
118.	12148271	4/17/2008	CIRCUITIZED SUBSTRATES
			UTILIZING SMOOTH-SIDED
			CONDUCTIVE LAYERS AS
			PART THEREOF
119.	11598647	11/14/2006	MULTILAYERED
			LAMINATE ASSEMBLY
			PROCESS
120.	11730212	3/30/2007	HASL ALTERNATIVE
			PROCESSING FOR
101		0.6.6.6.0.0	WIREBOND PACKAGES
121.	11727314	3/26/2007	ELECTRONIC PACKAGE
			WITH SHRINKING
122.	11882149	7/31/2007	ADHESIVE STRUCTURE AND METHOD
122.	11884149	7/31/2007	FOR OPTIMIZED
			ADHESION OF GOLD
			SURFACES TO
			ELECTRONIC DEVICES
123.	11783306	4/9/2007	STACKED CHIP PACKAGE
124.	11808140	6/7/2007	METHOD AND STRUCTURE
			FOR OUT OF THE PLANE
			PWB
125.	11730404	4/2/2007	FORMED LED CIRCUIT
			BOARD HEAT SINK
126.	11878673	7/26/2007	MULTILAYER EMBEDDED
			CAPACITORS (MLECS)
127.	12007704	1/15/2008	COST EFFECTIVE LARGE
			BOARD STRUCTURE AND
			BUILD METHODOLOGY
128.	12078206	3/28/2008	Z-INTERCONNECT JOINING
			STRUCTURE AND METHOD
120	10015050	C/0.1/0.000	FOR HIGH SPEED PWBS
129.	12215079	6/24/2008	SPRING ACTUATED LGA
<u></u>			CLAMPING MECHANISM

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**RECORDED: 12/03/2008**